PCN	Number:	201806290	01		PCN Date:	J	uly :	2, 2018	3	
Title	Datasheet for	- OPA837, O	PA2	837						
Cust	omer Contact:	PCN Manage	<u>er</u>				De	pt:	Quality Servic	es
Change Type:										
	Assembly Site			Design				Wafer	· Bump Site	
	Assembly Process		\square	Data Sheet				Wafer Bump Materia		
Assembly Materials				Part number change				Wafer Bump Process		
Mechanical Specification				Test Site				Wafer Fab Site		
Packing/Shipping/Labeling				Test Process				Wafer Fab Materials		
	Wafer Fab Process							Fab Process		
Notification Details										
Description of Change:										
	s Instruments Inco	•		-			y nc	otificatio	on.	
	product datasheet(w.				
The f	ollowing change h	istory provid	es f	urther det	ails.					
TEXAS INSTRUMENTS OPA837, OPA2837										
	INSTRUMENTS					SBO	5673/		OPA837, OP IBER 2017-REVISED AF	
Chan	ges from Original (Sep	otember 2017) t	o Re	vision A		500	0010/	- JEFTER	IDEN 2017 - NEVIOLD AF	Page
	ided OPA2837 to docu									
	dded Single-Supply Ope									
	onanged i or o to i mich page igare									
	Added footnote to Pin Functions table									
	Changed footnote describing method of computation of slew rate in Electrical Characteristics: $V_S = 5 V$ table									
	Changed default test condition in Electrical Characteristics: $V_s = 3 V$ table									
	Changed footnote describing method of computation of slew rate in Electrical Characteristics: V _S = 3 V table									
	Changed values for common-mode input range, high in Electrical Characteristics: V _S = 3 V table									
	Response Flatness vs Gain figures 10 Changed gain –1 V/V to gain –2 V/V, swapped legend colors in Inverting Overdrive Recovery figure 11									
										13
	Flatness vs Gain figure conditions									
• Ch								15		
• Ch							15			
• Ch	Changed y-axis caption in Tum-On Time to Sinusoidal Input and Turn-Off Time to Sinusoidal Input figures							18		
	Changed EVM link in Split-Supply Operation section from OPA837DBV to OPA835DBV									
	· · · · · · · · · · · · · · · · · · ·									
Changed 1 SPS to 1 MSPS in OPA837 and ADS8860 Example Circuit figure										
	latasheet number	will be chang	ging							
Devi	ice Family			Cha	ange From:			Change	e To:	
OPA837, OPA2837 SBOS673 SBOS673A							573A			
These changes may be reviewed at the datasheet links provided.										
http://www.ti.com/product/OPA837										
Reason for Change:										
To accurately reflect device characteristics.										
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):										
No anticipated impact. This is a specification change announcement only. There are no changes to										
the actual device.										

Changes to product identification resulting from this PCN:								
None.								
Product Affected:								
OPA2837IDGKR	OPA2837IDGKT	OPA837IDBVR	OPA837IDBVT					
OPA837IDCKR	OPA837IDCKT							

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
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